

1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings†

Drain-to-Source Voltage	BV_{DSX}
Drain-to-Gate Voltage	BV_{DGX}
Gate-to-Source Voltage	$\pm 20V$
Operating Ambient Temperature, T_A	$-55^{\circ}C$ to $+150^{\circ}C$
Storage Temperature, T_S	$-55^{\circ}C$ to $+150^{\circ}C$

† **Notice:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

Electrical Specifications: $T_A = 25^{\circ}C$ unless otherwise specified. All DC parameters are 100% tested at $25^{\circ}C$ unless otherwise stated. Pulse test: 300 μs pulse, 2% duty cycle

Parameter	Sym.	Min.	Typ.	Max.	Unit	Conditions
Drain-to-Source Breakdown Voltage	BV_{DSX}	250	—	—	V	$V_{GS} = -5V$, $I_D = 100 \mu A$
Gate-to-Source Off Voltage	$V_{GS(OFF)}$	-1.5	—	-3.5	V	$V_{DS} = 15V$, $I_D = 1 mA$
Change in $V_{GS(OFF)}$ with Temperature	$\Delta V_{GS(OFF)}$	—	—	-4.5	mV/ $^{\circ}C$	$V_{DS} = 15V$, $I_D = 1 mA$ (Note 1)
Gate Body Leakage Current	I_{GSS}	—	—	100	nA	$V_{GS} = \pm 20 V$, $V_{DS} = 0V$
Drain-to-Source Leakage Current	$I_{D(OFF)}$	—	—	1	μA	$V_{DS} = \text{Maximum rating}$, $V_{GS} = -5V$
		—	—	1	mA	$V_{DS} = 0.8 \text{ Maximum rating}$, $V_{GS} = -5V$, $T_A = 125^{\circ}C$ (Note 1)
Saturated Drain-to-Source Current	I_{DSS}	300	—	—	mA	$V_{GS} = 0V$, $V_{DS} = 15V$
Static Drain-to-Source On-State Resistance	$R_{DS(ON)}$	—	—	6	Ω	$V_{GS} = 0V$, $I_D = 200 mA$
Change in $R_{DS(ON)}$ with Temperature	$\Delta R_{DS(ON)}$	—	—	1.1	%/ $^{\circ}C$	$V_{GS} = 0V$, $I_D = 200 mA$ (Note 1)

Note 1: Specification is obtained by characterization and is not 100% tested.

AC ELECTRICAL CHARACTERISTICS

Electrical Specifications: $T_A = 25^\circ\text{C}$ unless otherwise specified. Specification is obtained by characterization and is not 100% tested.

Parameter	Sym.	Min.	Typ.	Max.	Unit	Conditions
Forward Transconductance	G _{FS}	225	—	—	mmho	V _{DS} = 10V, I _D = 150 mA
Input Capacitance	C _{ISS}	—	270	350	pF	V _{GS} = −5V, V _{DS} = 25V, f = 1 MHz
Common Source Output Capacitance	C _{OSS}	—	20	60	pF	
Reverse Transfer Capacitance	C _{RSS}	—	5	20	pF	
Turn-On Delay Time	t _{d(ON)}	—	—	20	ns	V _{DD} = 25V, I _D = 150 mA, R _{GEN} = 25Ω, V _{GS} = 0V to −10V
Rise Time	t _r	—	—	25	ns	
Turn-Off Delay Time	t _{d(OFF)}	—	—	25	ns	
Fall Time	t _f	—	—	40	ns	
DIODE PARAMETER						
Diode Forward Voltage Drop	V _{SD}	—	—	1.8	V	V _{GS} = −5V, I _{SD} = 150 mA (Note 1)
Reverse Recovery Time	t _{rr}	—	800	—	ns	V _{GS} = −5V, I _{SD} = 150 mA

Note 1: Unless otherwise stated, all DC parameters are 100% tested at 25°C . Pulse test: 300 μs pulse, 2% duty cycle

TEMPERATURE SPECIFICATIONS

Parameter	Sym.	Min.	Typ.	Max.	Unit	Conditions
TEMPERATURE RANGE						
Operating Ambient Temperature	T_A	-55	—	+150	$^\circ\text{C}$	
Storage Temperature	T_S	-55	—	+150	$^\circ\text{C}$	
PACKAGE THERMAL RESISTANCE						
3-lead SOT-89	θ_{JA}	—	133	—	$^\circ\text{C/W}$	

THERMAL CHARACTERISTICS

Package	I_D (Note 1) (Continuous) (mA)	I_D (Pulsed) (A)	Power Dissipation at $T_A = 25^\circ\text{C}$ (Note 2) (W)	I_{DR} (Note 1) (mA)	I_{DRM} (A)
3-lead SOT-89	360	1	1.6	360	1

Note 1: I_D (continuous) is limited by maximum T_J .

2: Mounted on an FR4 board, 25 mm x 25 mm x 1.57 mm

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g. outside specified power supply range) and therefore outside the warranted range.

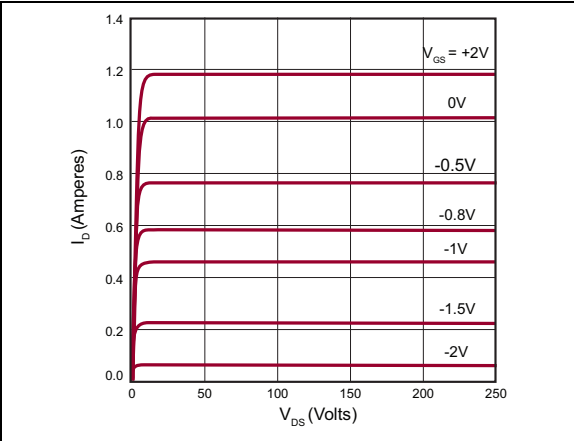


FIGURE 2-1: Output Characteristics.

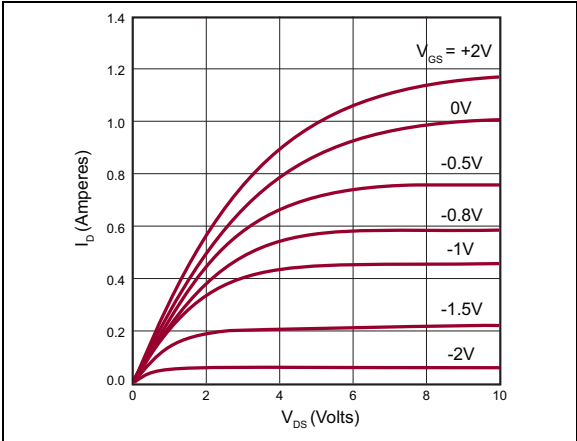


FIGURE 2-4: Saturation Characteristics.

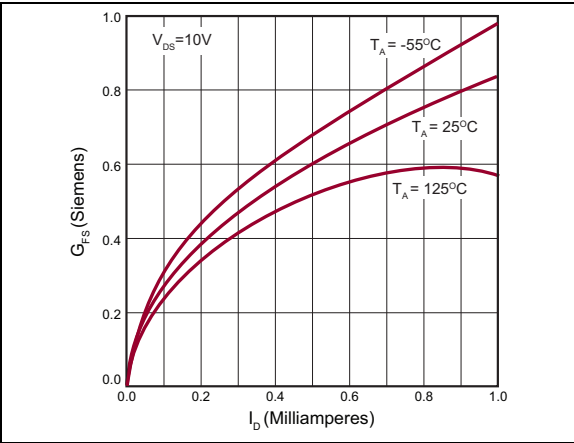


FIGURE 2-2: Transconductance vs. Drain Current.

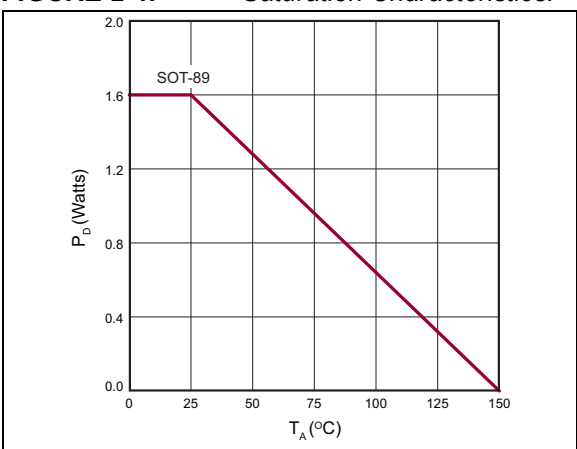


FIGURE 2-5: Power Dissipation vs. Ambient Temperature.

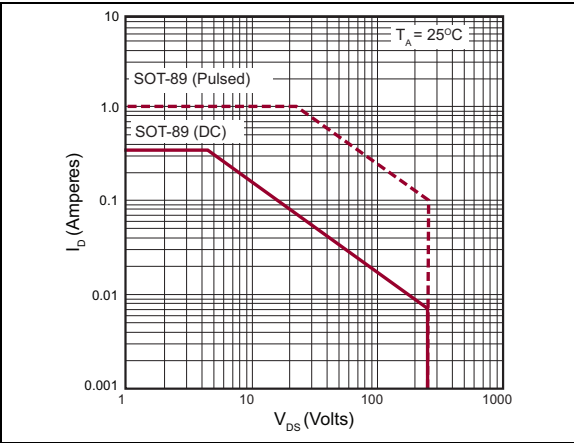


FIGURE 2-3: Maximum Rated Safe Operating Area.

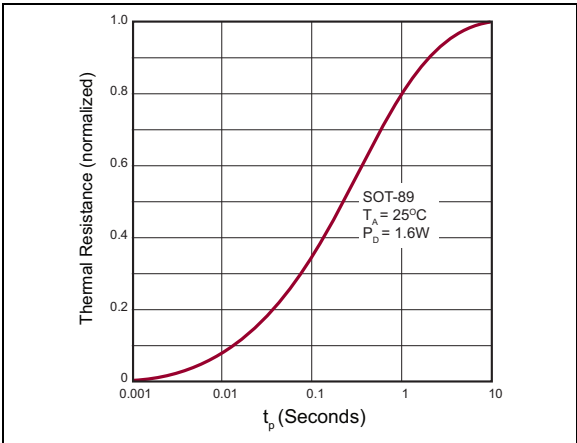


FIGURE 2-6: Thermal Response Characteristics.

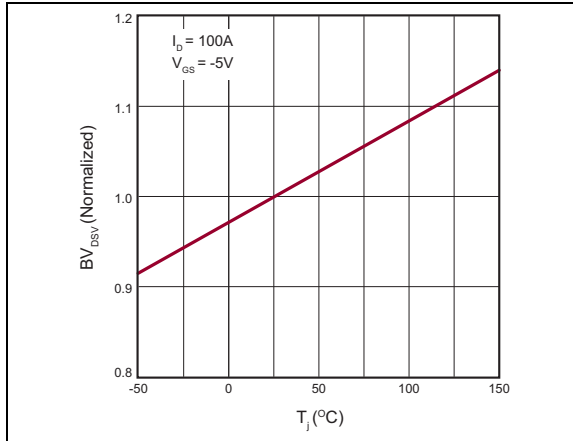


FIGURE 2-7: BV_{DSV} Variation with Temperature.

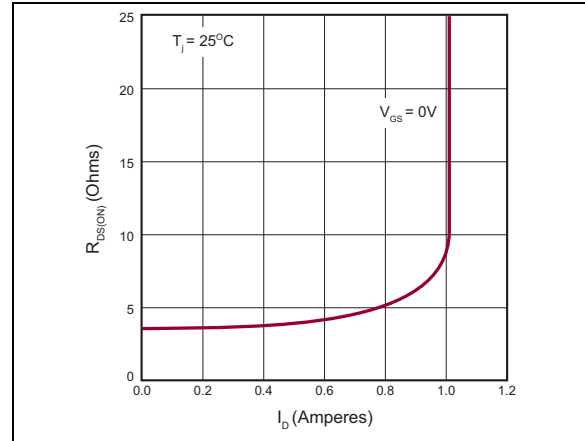


FIGURE 2-10: On-Resistance vs. Drain Current.

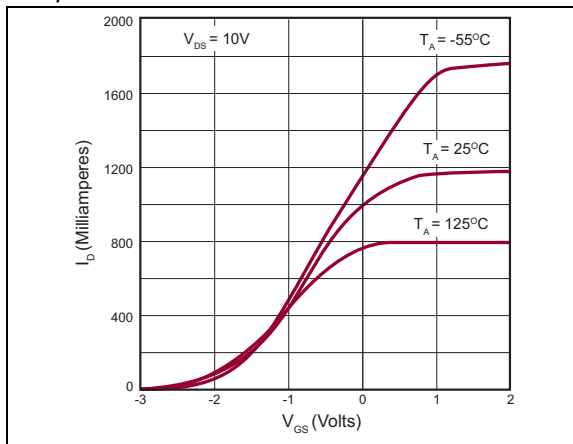


FIGURE 2-8: Transfer Characteristics.

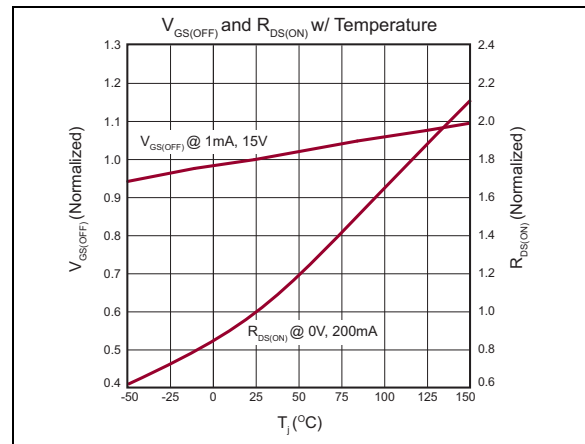


FIGURE 2-11: $V_{GS(OFF)}$ and $R_{DS(ON)}$ with Temperature.

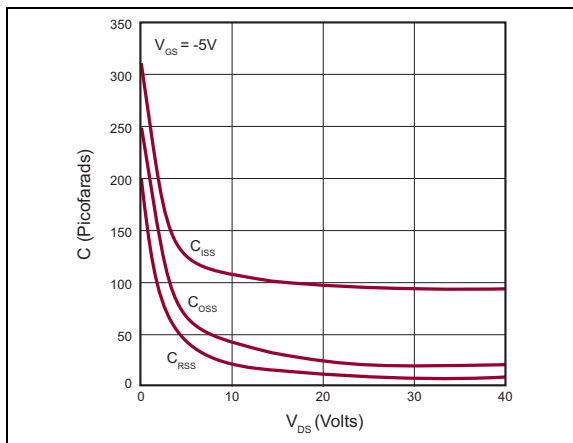


FIGURE 2-9: Capacitance vs. Drain-to-Source Voltage.

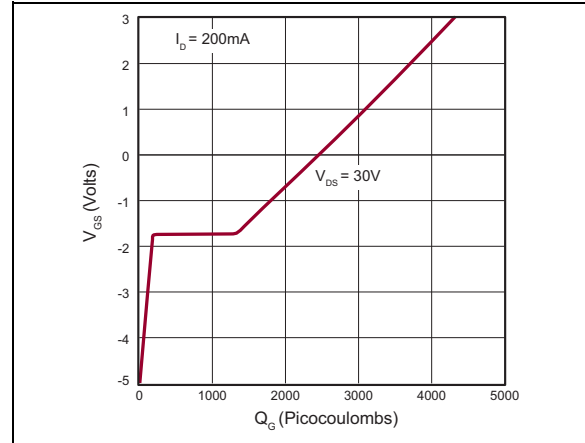


FIGURE 2-12: Gate Drive Dynamic Characteristics.

DN3525

3.0 PIN DESCRIPTION

Table 3-1 shows the description of pins in DN3525.
Refer to [Package Type](#) for the location of pins.

TABLE 3-1: PIN FUNCTION TABLE

Pin Number	Pin Name	Description
1	Gate	Gate
2, 4	Drain	Drain
3	Source	Source

4.0 FUNCTIONAL DESCRIPTION

Figure 4-1 illustrates the switching waveforms and test circuit for DN3525.

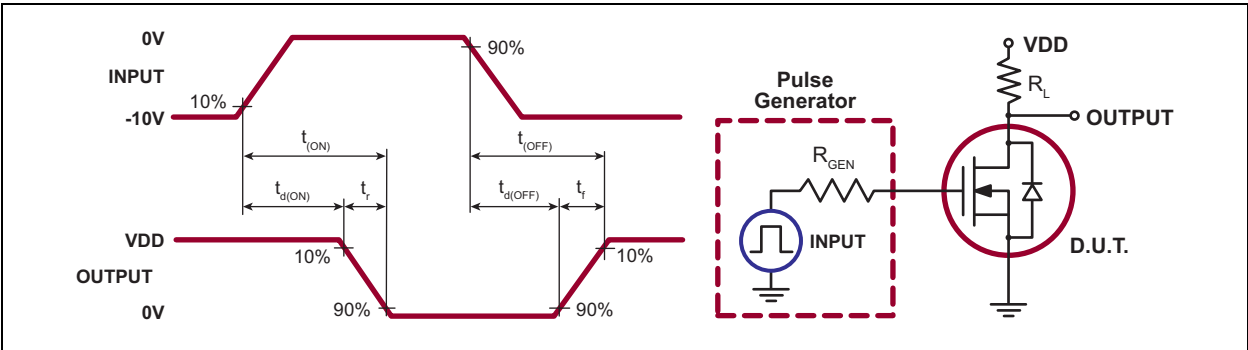


FIGURE 4-1: Switching Waveforms and Test Circuit.

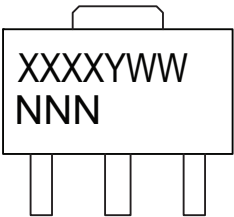
TABLE 4-1: PRODUCT SUMMARY

BV_{DSX}/BV_{DGX} (mA)	$R_{DS(ON)}$ (Maximum) (Ω)	I_{DSS} (Minimum) (mA)
250	6	300

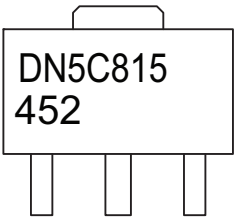
5.0 PACKAGING INFORMATION

5.1 Package Marking Information

3-lead SOT-89

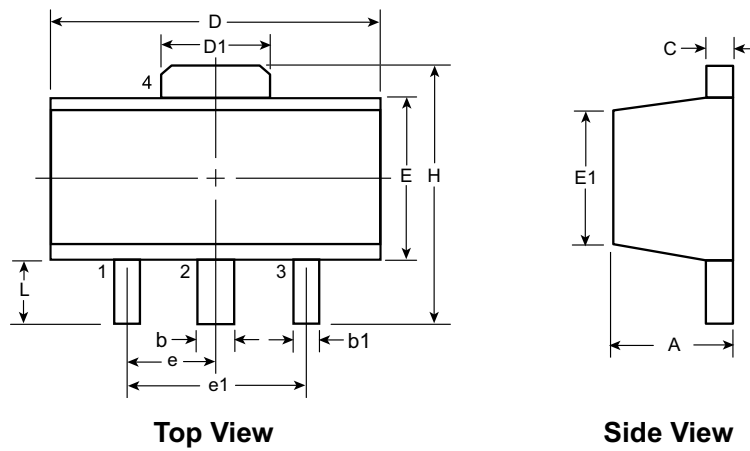


Example



Legend:	XX...X	Product Code or Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.
Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for product code or customer-specific information. Package may or not include the corporate logo.		

3-Lead TO-243AA (SOT-89) Package Outline (N8)



Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

Symbol		A	b	b1	C	D	D1	E	E1	e	e1	H	L
Dimensions (mm)	MIN	1.40	0.44	0.36	0.35	4.40	1.62	2.29	2.00†	1.50 BSC	3.00 BSC	3.94	0.73†
	NOM	-	-	-	-	-	-	-	-			-	-
	MAX	1.60	0.56	0.48	0.44	4.60	1.83	2.60	2.29			4.25	1.20

JEDEC Registration TO-243, Variation AA, Issue C, July 1986.

† This dimension differs from the JEDEC drawing

Drawings not to scale.

DN3525

NOTES:

APPENDIX A: REVISION HISTORY

Revision A (May 2018)

- Converted Supertex Doc# DSFP-DN3525 to Microchip DS20005705A
- Added a pin function table
- Changed the package marking format
- Made minor text changes throughout the document

DN3525

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

<u>PART NO.</u>	<u>XX</u>	-	<u>X</u>	-	<u>X</u>
Device	Package Options		Environmental		Media Type
Device:	DN3525	=	N-Channel Depletion-Mode Vertical DMOS FET		
Package:	N8	=	3-lead SOT-89		
Environmental:	G	=	Lead (Pb)-free/RoHS-compliant Package		
Media Type:	(blank)	=	2000/Reel for an N8 Package		
Example:					
a) DN3525N8-G: N-Channel Depletion-Mode Vertical DMOS FET, 3-lead SOT-89, 2000/Reel					

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